505697209 09/27/2019

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5744019

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SANG HYUK LEE	09/23/2019
SANG SOON LEE	09/18/2019
JANG PIL LEE	09/18/2019
JONG KUK LEE	09/18/2019

RECEIVING PARTY DATA

Name:	DOOSAN HEAVY INDUSTRIES & CONSTRUCTION CO., LTD.
Street Address:	22, DOOSANVOLVO-RO, SEONGSAN-GU
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State/Country:	KOREA, REPUBLIC OF
Postal Code:	51711
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Street Address:	1 RIVER ROAD, SCHENECTADY
City:	NEW YORK
State/Country:	NEW YORK
Postal Code:	12345

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	16586878	

CORRESPONDENCE DATA

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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NAME OF SUBMITTER:	DANIEL CHUNG
SIGNATURE:	/Daniel CHUNG/

PATENT 505697209 REEL: 050581 FRAME: 0434

 DATE SIGNED:
 09/27/2019

 Total Attachments: 2
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PATENT REEL: 050581 FRAME: 0435

ASSIGNMENT OF PATENT APPLICATION

WHEREAS, the below named individual(s), hereinafter referred to as "Assignors," are the inventor(s) of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention:

Stud Connection Structure for Noise Reducing Wall

Filing Date:

indicated.

September 27, 2019

Application No.:

16/586,878

WHEREAS, DOOSAN HEAVY INDUSTRIES & CONSTRUCTION CO.

LTD., located at 22, Doosanvolvo-ro, Seongsan-gu, Changwon-si, Gyeongsangnam-do, 51711 Republic of Korea and GENERAL ELECTRIC COMPANY, located at 1 River Road, Schenectady, New York 12345, U.S.A., hereinafter referred to as "ASSIGNEE," is desirous of acquiring ASSIGNORS' interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have sold, assigned and transferred, and by these presents do sell, assign and transfer unto the said Assignees, and Assignees' successors and assigns, all their right, title and interest in and to the said invention and application including any corresponding foreign application, and in and to any Letters Patent which may hereafter be granted on the same in the United States and any corresponding foreign application, the said interest to be held and enjoyed by said Assignees as fully and exclusively as it would have been held and enjoyed by said Assignors had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in Assignee, or Assignee's successors and assigns. Assignors bereby authorize and request INVENSTONE PATENT, LLC, 8408 Arlington BLVD Suite 203, FAIRFAX VA 22031 U.S.A., to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates

Legal Name	of Inventor:	LEE, Sang	Hyuk	
Signature:	24	Sur	Date	September 23, 2019

PATENT REEL: 050581 FRAME: 0436

Legal Name of Inventor:	LEE, Sang Soon		1	
Signature:	Bu	Date:	2019.	9. 18
Legal Name of Inventor:	LEE, Jang Pil			
Signature:	lee 1	Date:	`2019	9.18
Legal Name of Inventor:	LEE, Jong Kuk			· · · · · · · · · · · · · · · · · · ·
Simulation	2	Datas	2019	9 18